1. Product profile

1.1 General description
Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD1608 (DFN1608D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits
- Average forward current: $I_{F(AV)} \leq 1.5$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage $V_F \leq 420$ mV
- Low reverse current
- AEC-Q101 qualified
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package

1.3 Applications
- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Low power consumption applications
- Ultra high-speed switching
- Reverse polarity protection

1.4 Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{F(AV)}$</td>
<td>average forward current</td>
<td>$\delta &lt; 0.5$; $f = 20$ kHz; $T_{amb} \leq 100$ °C; square wave</td>
<td>-</td>
<td>-</td>
<td>1.5 A</td>
<td></td>
</tr>
<tr>
<td></td>
<td></td>
<td>$\delta &lt; 0.5$; $f = 20$ kHz; $T_{sp} \leq 140$ °C; square wave</td>
<td>-</td>
<td>-</td>
<td>1.5 A</td>
<td></td>
</tr>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>$T_j = 25$ °C</td>
<td>-</td>
<td>-</td>
<td>20 V</td>
<td></td>
</tr>
<tr>
<td>$V_F$</td>
<td>forward voltage</td>
<td>$I_F = 1.5$ A; pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$; $T_j = 25$ °C</td>
<td>-</td>
<td>375</td>
<td>420 mV</td>
<td></td>
</tr>
<tr>
<td>$I_R$</td>
<td>reverse current</td>
<td>$V_R = 10$ V; $T_j = 25$ °C</td>
<td>-</td>
<td>70</td>
<td>350 µA</td>
<td></td>
</tr>
<tr>
<td>$t_{tr}$</td>
<td>reverse recovery time</td>
<td>$I_R = 0.5$ A; $I_F = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C</td>
<td>-</td>
<td>5</td>
<td>- ns</td>
<td></td>
</tr>
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</table>

2. Pinning information

Table 2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>K</td>
<td>cathode[^1]</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>A</td>
<td>anode</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

[^1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Name</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG2015EPK</td>
<td>DFN1608D-2</td>
<td>Leadless ultra small plastic package; 2 terminals</td>
<td>SOD1608</td>
<td></td>
</tr>
</tbody>
</table>

4. Marking

Table 4. Marking codes

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>PMEG2015EPK</td>
<td>1100 0000</td>
</tr>
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</table>

Fig 1. SOD1608 binary marking code description
5. Limiting values

### Table 5. Limiting values

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>$T_j = 25 \degree C$</td>
<td>-</td>
<td>20</td>
<td>V</td>
</tr>
<tr>
<td>$I_F$</td>
<td>forward current</td>
<td>$T_{sp} \leq 135 \degree C$</td>
<td>-</td>
<td>2.1</td>
<td>A</td>
</tr>
<tr>
<td>$I_{F(AV)}$</td>
<td>average forward current</td>
<td>$\delta &lt; 0.5; f = 20 kHz; \text{square wave}; T_{amb} \leq 100 \degree C$</td>
<td>-</td>
<td>1.5</td>
<td>A</td>
</tr>
<tr>
<td>$I_{FRM}$</td>
<td>repetitive peak forward current</td>
<td>$t_p = 1 \text{ ms}; \delta = 0.25$</td>
<td>-</td>
<td>4</td>
<td>A</td>
</tr>
<tr>
<td>$I_{FSM}$</td>
<td>non-repetitive peak forward current</td>
<td>$t_p = 8 \text{ ms}; T_{j(init)} = 25 \degree C; \text{square wave}$</td>
<td>-</td>
<td>5</td>
<td>A</td>
</tr>
<tr>
<td>$P_{tot}$</td>
<td>total power dissipation</td>
<td>$T_{amb} \leq 25 \degree C$</td>
<td>-</td>
<td>415</td>
<td>mW</td>
</tr>
<tr>
<td>$T_j$</td>
<td>junction temperature</td>
<td></td>
<td>-</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>$T_{amb}$</td>
<td>ambient temperature</td>
<td></td>
<td>-55</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>$T_{stg}$</td>
<td>storage temperature</td>
<td></td>
<td>-65</td>
<td>150</td>
<td>°C</td>
</tr>
</tbody>
</table>

1. Device mounted on a ceramic Printed-Circuit Board (PCB), Al$_2$O$_3$, standard footprint.
2. Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
3. Reflow soldering is the only recommended soldering method.
4. Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm$^2$.

6. Thermal characteristics

### Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$R_{th(j-a)}$</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air</td>
<td>[1][2][3]</td>
<td>-</td>
<td>-</td>
<td>300</td>
</tr>
<tr>
<td>$R_{th(j-sp)}$</td>
<td>thermal resistance from junction to solder point</td>
<td></td>
<td>[1][4][5][6]</td>
<td>-</td>
<td>-</td>
<td>140</td>
</tr>
</tbody>
</table>

1. For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses $P_R$ are a significant part of the total power losses.
2. Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
3. Reflow soldering is the only recommended soldering method.
4. Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm$^2$.
5. Device mounted on a ceramic PCB, Al$_2$O$_3$, standard footprint.
6. Soldering point of cathode tab.
Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB, standard footprint

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB, mounting pad for cathode 1 cm²
7. Characteristics

Table 7. Characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>V&lt;sub&gt;F&lt;/sub&gt;</td>
<td>forward voltage</td>
<td>I&lt;sub&gt;f&lt;/sub&gt; = 100 mA; pulsed; t&lt;sub&gt;p&lt;/sub&gt; ≤ 300 µs; δ ≤ 0.02; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>230</td>
<td>260</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I&lt;sub&gt;f&lt;/sub&gt; = 500 mA; pulsed; t&lt;sub&gt;p&lt;/sub&gt; ≤ 300 µs; δ ≤ 0.02; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>290</td>
<td>330</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I&lt;sub&gt;f&lt;/sub&gt; = 1 A; pulsed; t&lt;sub&gt;p&lt;/sub&gt; ≤ 300 µs; δ ≤ 0.02; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>330</td>
<td>380</td>
<td>mV</td>
</tr>
<tr>
<td></td>
<td></td>
<td>I&lt;sub&gt;f&lt;/sub&gt; = 1.5 A; pulsed; t&lt;sub&gt;p&lt;/sub&gt; ≤ 300 µs; δ ≤ 0.02; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>375</td>
<td>420</td>
<td>mV</td>
</tr>
<tr>
<td>I&lt;sub&gt;R&lt;/sub&gt;</td>
<td>reverse current</td>
<td>V&lt;sub&gt;R&lt;/sub&gt; = 10 V; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>70</td>
<td>350</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V&lt;sub&gt;R&lt;/sub&gt; = 20 V; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>220</td>
<td>900</td>
<td>μA</td>
</tr>
<tr>
<td>C&lt;sub&gt;d&lt;/sub&gt;</td>
<td>diode capacitance</td>
<td>V&lt;sub&gt;R&lt;/sub&gt; = 1 V; f = 1 MHz; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>105</td>
<td>120</td>
<td>pF</td>
</tr>
<tr>
<td></td>
<td></td>
<td>V&lt;sub&gt;R&lt;/sub&gt; = 10 V; f = 1 MHz; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>40</td>
<td>50</td>
<td>pF</td>
</tr>
<tr>
<td>t&lt;sub&gt;rr&lt;/sub&gt;</td>
<td>reverse recovery time</td>
<td>I&lt;sub&gt;f&lt;/sub&gt; = 0.5 A; I&lt;sub&gt;R&lt;/sub&gt; = 0.5 A; I&lt;sub&gt;R&lt;/sub&gt;(&lt;sub&gt;meas&lt;/sub&gt;) = 0.1 A; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>5</td>
<td>-</td>
<td>ns</td>
</tr>
<tr>
<td>V&lt;sub&gt;FRM&lt;/sub&gt;</td>
<td>peak forward recovery</td>
<td>I&lt;sub&gt;f&lt;/sub&gt; = 0.5 A; dI&lt;sub&gt;f&lt;/sub&gt;/dt = 20 A/µs; T&lt;sub&gt;j&lt;/sub&gt; = 25 °C</td>
<td>-</td>
<td>320</td>
<td>-</td>
<td>mV</td>
</tr>
</tbody>
</table>
Fig 5. Forward current as a function of forward voltage; typical values

(1) $T_j = 150 \ °C$
(2) $T_j = 125 \ °C$
(3) $T_j = 85 \ °C$
(4) $T_j = 25 \ °C$
(5) $T_j = -40 \ °C$

Fig 6. Reverse current as a function of reverse voltage; typical values

(1) $T_j = 125 \ °C$
(2) $T_j = 85 \ °C$
(3) $T_j = 25 \ °C$
(4) $T_j = -40 \ °C$

Fig 7. Diode capacitance as a function of reverse voltage; typical values

$f = 1 \ MHz; T_\text{amb} = 25 \ °C$

Fig 8. Average forward power dissipation as a function of average forward current; typical values

$T_j = 150 \ °C$
(1) $\delta = 0.1$
(2) $\delta = 0.2$
(3) $\delta = 0.5$
(4) $\delta = 1$
20 V, 1.5 A low VF MEGA Schottky barrier rectifier

**Fig 9.** Average reverse power dissipation as a function of reverse voltage; typical values

**Fig 10.** Average forward current as a function of ambient temperature; typical values

**Fig 11.** Average forward current as a function of ambient temperature; typical values

**Fig 12.** Average forward current as a function of ambient temperature; typical values
8. Test information

$$T_j = 150 \, ^\circ\text{C}$$

(1) $\delta = 1$ (DC)

(2) $\delta = 0.5; \, f = 20 \, \text{kHz}$

(3) $\delta = 0.2; \, f = 20 \, \text{kHz}$

(4) $\delta = 0.1; \, f = 20 \, \text{kHz}$

Fig 13. Average forward current as a function of solder point temperature; typical values

Fig 14. Reverse recovery definition
The current ratings for the typical waveforms are calculated according to the equations:
\[ I_{F(AV)} = I_M \times \delta \]
with \( I_M \) defined as peak current, \( I_{RMS} = I_{F(AV)} \) at DC, and \( I_{RMS} = I_M \times \sqrt{\delta} \) with \( I_{RMS} \) defined as RMS current.

### 8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.
9. Package outline

Fig 17. Package outline SOD1608 (DFN1608D-2)

10. Soldering

Footprint information for reflow soldering of SOD1608 package

Fig 18. Reflow soldering footprint for SOD1608 (DFN1608D-2)
11. Revision history

<table>
<thead>
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<th>Document ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
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<td>20120306</td>
<td>Product data sheet</td>
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12. Legal information

12.1 Data sheet status

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<tbody>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
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</table>

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL: http://www.nxp.com.

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For more information, please visit: http://www.nxp.com

For sales office addresses, please send an email to: salesaddresses@nxp.com
14. Contents

1  Product profile ........................................... 1
   1.1  General description ................................. 1
   1.2  Features and benefits ............................... 1
   1.3  Applications ......................................... 1
   1.4  Quick reference data ............................... 1
2  Pinning information ................................. 2
3  Ordering information ............................... 2
4  Marking ................................................ 2
5  Limiting values ........................................ 3
6  Thermal characteristics .............................. 3
7  Characteristics .......................................... 5
8  Test information ...................................... 8
   8.1  Quality information ................................. 9
9  Package outline ...................................... 10
10 Soldering ............................................... 10
11 Revision history ...................................... 11
12 Legal information .................................... 12
   12.1  Data sheet status ................................ 12
   12.2  Definitions ......................................... 12
   12.3  Disclaimers ........................................ 12
   12.4  Trademarks ......................................... 13
13 Contact information ................................ 13